

N Channel Power MOSFET with extremely low $R_{DS(ON)}$

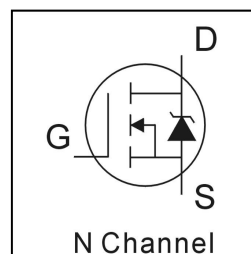
Chip Specification

General Description:

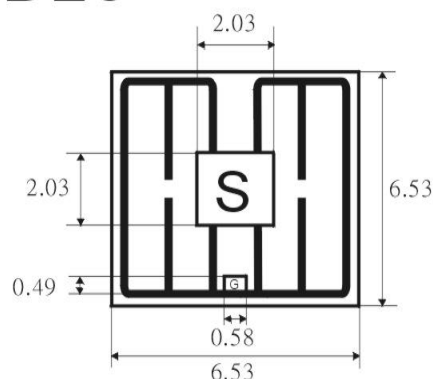
- * Advanced Process Technology
- * Dynamic dV/dt Rating
- * **175°C Operating Temperature**
- * **Fast Switching**
- * **Fully Avalanche Rated**
- * **Extremely low $R_{DS(ON)}$**

Mechanical Data:

D26	
Dimension	6.53mm x 6.53mm
Thickness:	400 μm
Metallization:	
Top :	Al
Backside :	CrNiAg / Au
Suggested Bonding Conditions:	
Die Mounting:	Solder Perform
95/5 PbSn or 92.5./2.5/5 PbAgIn	
Source Bonding Wire:	25 mil Al



D26



60V, N Channel

Absolute Maximum Rating

@ $T_a=25^{\circ}\text{C}$

Characteristics	Symbol	Limit	Unit	Test Conditions
Drain-to-Source Breakdown Voltage	$V(BR)_{DSS}$	60	V	$V_{GS}=0V$, $I_D=250\mu A$
Static Drain-to - Source On-resistance	$R_{DS(ON)}$	0.014	Ω	$V_{GS}=10V$, $I_D=54A$
Continuous Drain current (in target package)	$I_D@25^{\circ}\text{C}$	70	A	$V_{GS}=10V$
Continuous Drain current (in target package)	$I_D@100^{\circ}\text{C}$	64	A	$V_{GS}=10V$
Operation Junction	T_J	-55~175	$^{\circ}\text{C}$	
Storage Temperature	T_{STR}	-55~175	$^{\circ}\text{C}$	

Target Device: IRFP054

TO-247AC

 P_D

230

W

@ $T_c=25^{\circ}\text{C}$